

<b>Product Specification</b> (产品规格书)	<b>Issued By:</b> <b>Engineering Dept.</b>				
	<b>Subject (主题):</b> 2.54mm Pitch KR2542 Series Board To Board Connector Specification	<table border="1"> <tr> <td><b>Date Issued</b></td> <td>2022/2/26</td> </tr> <tr> <td><b>Date Revised</b></td> <td>2022/2/26</td> </tr> </table>	<b>Date Issued</b>	2022/2/26	<b>Date Revised</b>
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**1.0 适用范围 (Scope)**

此种规格包括2.54mm Pitch KR2542 Series 连接器规格说明.

This Specification Covers the 2.54mm Pitch KR2542 Series Connector Specification.

**2.0 规格与料号 (Spec and Part number)**

规格内容 <b>Specification</b>	产品料号 <b>Production No.</b>	产品图示 <b>Picture of Product</b>
胶壳/Housing	None	
端子/Terminal	None	
针座/Wafer	C2542FD1**10G01***C C2542FD2**10G01****C C2542FS2**10G01**RC C2542RD1**10G01**PC C2542RD2**10G01**PC C2542VD1**10G01**PC C2542VD2**10G01**PC	

**3.0 材质与表面处理 (Disposal of Material and surface)**

规格内容 <b>Specification</b>		材质 <b>Materials</b>	表面处理 <b>Disposal of Surface</b>
胶壳/Housing		N/A	N/A
端子/Terminal		N/A	N/A
针座/ Wafer	SMT Type	主体 Base	PA6T
		导体 Contact	Phosphor Bronze Or Brass
		固定片 Solder tab	N/A
	DIP Type	主体 Base	PBT or PA6T
		导体 Contact	Phosphor Bronze Or Brass
		固定片 Solder tab	N/A

(以上参数请以工程图为准/Please Refer to the Project drawing for the above Specification)

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#### 4.0 额定等级 (Ratings and applicable wires)

项 目 Item	规 格 Standard	
额定电压Rated Voltage (Max.)	250V	AC/DC
额定电流Rated Current (Max.)	3A	
使用温度范围Ambient temperature Range	-40°C~+105°C	
适用线径Applicable wire insulation O.D	N/A	

#### 5.0 电气性能 (Electrical Performance)

项 目 Item	条 件 Test Condition	规 格 Requirement
5.1 接触阻抗 Contact Resistance	公母配合,开放电压 20mV 最大,电流 100mA最大 检测连接器A~B 区. Mate connectors, measure by dry circuit, 20mV MAX, 100mA MAX. (Based upon EIA-364-23C)	20 milliohms Max.
5.2 绝缘阻抗 Insulation Resistance	公母配合,对相邻两接触导体,于1分钟内施 加500V 的直流电,并量测其间绝缘阻抗. Mate connectors, apply 500V DC for 1 minute between adjacent contacts to measure the insulation resistance. (Based upon EIA-364-21B)	1000 Megohms Min.
5.3 耐电压 Dielectric Strength	公母配合,在相邻端子或端子与接地端之 间,使用1500V 的交流电1 分钟,检测连接器. Mate connectors, apply 1500V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A)	无损毁或出现电火花 No Breakdown and Flashover

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**6.0 机械性能 (Mechanical Performance)**

项 目 Item	条 件 Test Condition	规 格 Requirement
6.1 插拔力 Insertion & Withdrawal Force	以每分钟25.4±3mm的速率插入和拔出。 (不包含卡榫结合力) Insert and withdraw connectors at the speed rate of 25.4±3mm/minute. (Excluding plastic detents) (Based upon EIA-364-13D)	单一接触点 Per Contact 插入力最大容许值: Insertion Force: 0.80 kgf Max. 拔出力最小容许值: Withdrawal Force: 0.05 kgf Min.
6.2 Pin 针保持力 Pin Retention Force(Female Header)	以每分钟 25.4±3mm的速率,将PIN针从 Wafer 内轴向拔出的力量。 Apply axial push force at the speed rate of 25.4±3mm/minute.	0.5 kgf (4.9 N) Min.

**7.0 环境性能及其它 (Environmental Performance and Others)**

项 目 Item	条 件 Test Condition	规 格 Requirement	
7.1 耐久性 Durability	以每分钟不超过10次的速率,将公母插拔30次。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute. (Based upon EIA-364-09C)	接触阻抗 Contact Resistance	40 milliohms Max.
7.2 温升测试 Temperature Rise	公母对插后,在通过额定电流下,所测定的温度。 Carrying rated current load. (Based upon EIA-364-70B)	温升测试 Temperature Rise	30°C Max.
7.3 耐振动性 Vibration	振幅: 1.5mm P-P 时间: 10~55~10 HZ in 1 minute 持续时间: 每轴向 2 小时 Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B)	外观 Appearance	无异状 No Damage
		接触阻抗 Contact Resistance	40 milliohms Max.
		瞬断 Discontinuity	1 micro-second Max.

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项 目 Item		条 件 Test Condition	规 格 Requirement	
7.4	耐冲击性 Shock	在 X.Y.Z 上 6 个方向上,以 490m/s2(50g) 冲击下各 3 回. 490m/s2{50g}, 3strokes in each X.Y.Z. axes. (Based upon EIA-364-27B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.
			瞬断 Discontinuity	1 micro- second Max.
7.5	耐热性 Heat Resistance	105±2°C,96 hours. (Based upon EIA-364-17B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.
7.6	耐寒性 Cold Resistance	-40±2°C,96 hours. ( Based upon EIA-364-59)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.
7.7	耐湿性 Humidity	温度: 40±2°C 湿度: 90~95%(RH) 持续时间: 96 hours Temperature: 40±2°C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.
			耐电压 Dielectric Strength	Must meet 5.3
7.8	热冲击 Thermal shock	以-40°C持续 30 分钟经室温5分钟,而后以 105°C持续 30 分钟再经室温5分钟为一个 循环,共循环5 次. One Cycle Consists Of: -40°C for 30 minutes. → Room Temp. 5 minutes, +105°C for 30minutes. → Room Temp. 5 minutes Total Cycles: 5 Cycles. (Based upon EIA-364-32B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.

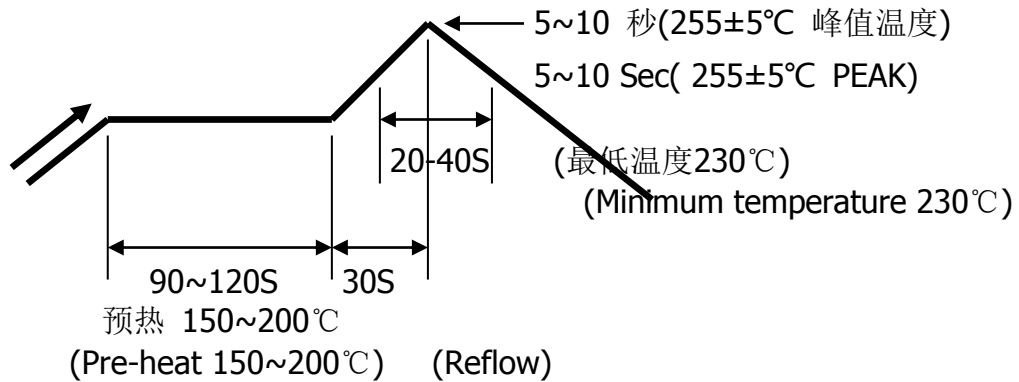
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项 目 <b>Item</b>		条 件 <b>Test Condition</b>	规 格 <b>Requirement</b>	
7.9	盐水喷雾 Salt Spray	在温度 $35\pm 2^{\circ}\text{C}$ ,盐水浓度 $5\pm 1\%$ 下,盐水喷雾24小时. 24 hours exposure to a salt spray from the $5\pm 1\%$ solution at $35\pm 2^{\circ}\text{C}$ . (Based upon EIA-364-26B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	40 milliohms Max.
7.10	焊锡附着性 Solder-ability	焊接时间: $3\pm 0.5$ 秒. 焊接温度: $245\pm 5^{\circ}\text{C}$ . Soldering Time: $3\pm 0.5$ second. Solder Temperature: $245\pm 5^{\circ}\text{C}$ . (Based upon EIA-364-52)	Solder Wetting	浸渍面积需 95%以上 95% of immersed area must show no voids, pin holes.
7.11	焊锡耐热性 Solder-Resistance	SMT型产品, 能够承受焊锡耐热范围. SMT type products, able to withstand the solder heat resistance range. 参考温度曲线图8.1 Refer to Temperature Profile8.1 (Based upon EIA-364-56D)	外观 Appearance	无异状 No Damage
		DIP型产品, 能够承受焊锡耐热范围. DIP type products, able to withstand the solder heat resistance range. 参考温度曲线图8.2 Refer to Temperature Profile8.2 (Based upon EIA-364-71B)	外观 Appearance	无异状 No Damage

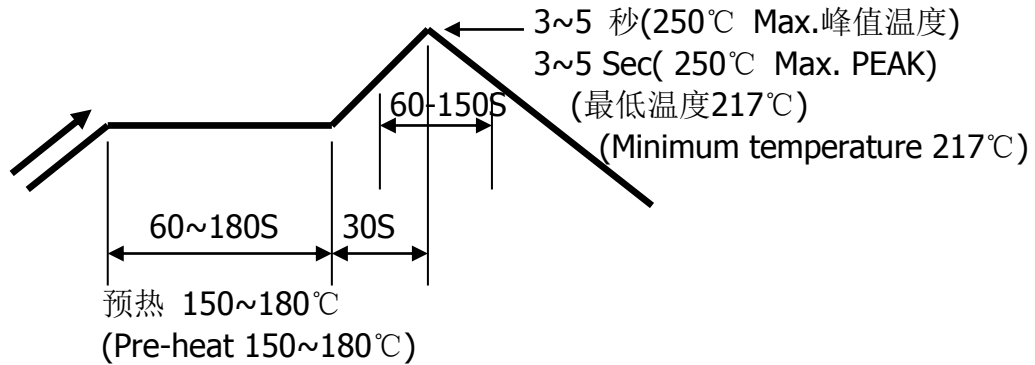
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**8.0 温度曲线 (Temperature Profile)**

**8.1 SMT红外线回流曲线(SMT Infrared Reflow Profile)**



**8.2 波峰焊曲线(Wave soldering profile)**



注：由于P.C板等焊接装置改变条件,所以请预先用自己的装置检查回流焊的条件.

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.

**9.0 备注 (Remark)**

有关规格书内容经变更或改版,如未能及时发布与通知,烦请联系我司业务人员提供产品最新资讯

Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.

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